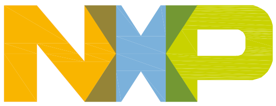

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MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: DFN, THERMALLY ENHANCED, 3 X 3 X 0.9, 0.65 PITCH, 8 TERMINAL	DOCUMENT NO: 98ASA00448D REV: A
	STANDARD: NON–JEDEC
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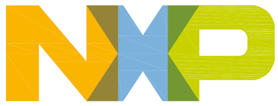

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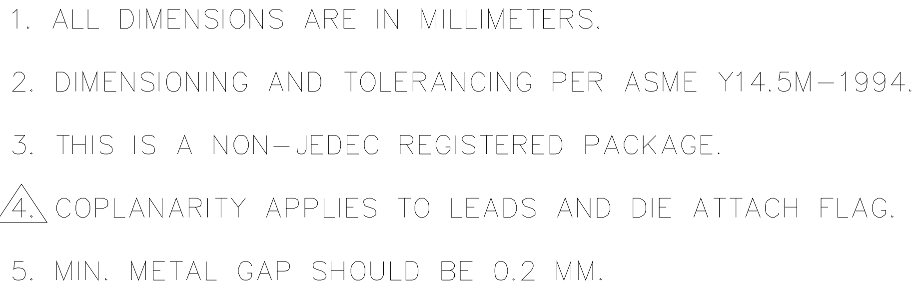

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THIS IS A NON–JEDEC REGISTERED PACKAGE.
4. (△) COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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